









Release Date: 22 January 2023 Version: A1.1

PRODUCT DATASHEET





- ► Ceramic High Power
- ➤ 3939 1.53t Series
- ► UVB (320~340nm)

N0Q61S26Z





3939 1.53t Series





FEATURES:

- Package: Ceramic SMT Package with Quartz Glass Lens
- Forward Current: 350mA Forward Voltage (typ.): 7.0V
- Radiant Power (typ.): 50mW@350mA
- Colour: Ultraviolet (UV) Wavelength: 320~340nm Viewing angle: 120°
- Materials:
 - Die: InGaN
 - Resin: Quartz Glass (Water Clear)
 - L/F: AIN
- Junction Temperature: +85°C
- Operating Temperature: -30~+60°C
- Storage Temperature: -40~+100°C
- **Grouping parameters:**
 - Forward voltage
 - Radiant power
 - Peak Wavelength
- Soldering methods: Reflow soldering
- MSL: Level 4 according to J-STD020
- Packing: 12mm tape with min.100pcs/reel, ø180mm (7")

APPLICATIONS:

- Disinfection
- Sterilization
- **Bio-Analysis**
- Detection
- Sensor Light
- Fluorescent Spectroscopy







CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Forward Current	I _{MAX}	350	mA
Junction Temperature	Tj	85	°C
Thermal Resistance Junction to Solder Point	R _{THJS}	12.5	°C/W
Electrostatic Discharge	ESD	2000	V
Operating Temperature	TOPR	-30~+60	°C
Storage Temperature	Тѕтс	-40~+100	°C
Solder Temperature	T _{SOL}	245	°C

Electrical & Optical Characteristics (Ta=25°C)

Parameter Symbol		Values			Unit	Test
Parameter Symbol	Min.	Тур.	Max.	Onit	Condition	
Forward Voltage	VF	5.0		9.0	V	I _F =350mA
Radiant Power	Po	30		70	mW	I _F =350mA
Peak Wavelength	WP	320		340	nm	I _F =350mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =350mA

^{1.} Radiant Power (Po) $\pm 10\%$, Forward Voltage (V_F) $\pm 0.2V$, Viewing angle($2\theta_{1/2}$) $\pm 10^{\circ}$, Wavelength (nm) ± 2 nm

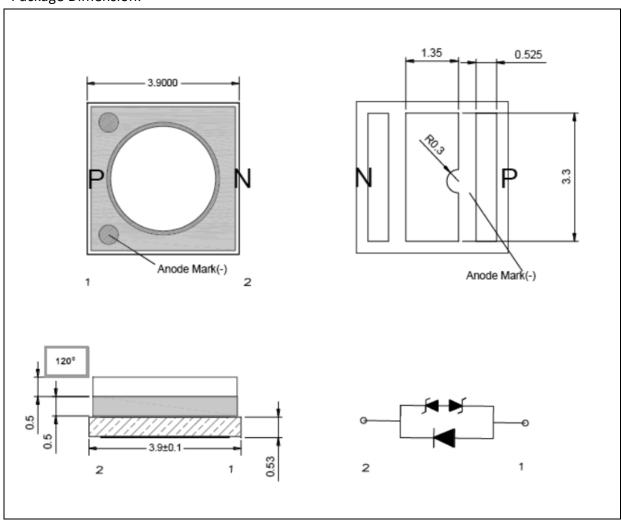






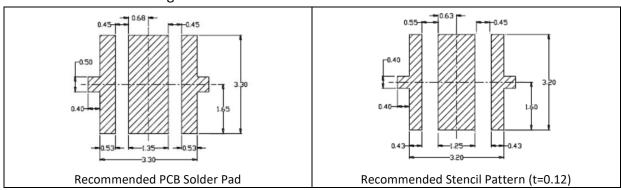
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.13 mm with angle tolerance $\pm 0.5^{\circ}$.







BINNING GROUPS:

Forward Voltage Classifications (I_F = 350mA):

Code	Min.	Max.	Unit
V1	5.0	7.0	V
V2	7.0	9.0	V

Radiant Power Classifications ($I_F = 350mA$):

Code	Min.	Max.	Unit
A1	30	50	
A2	50	70	mW

Peak Wavelength Classifications (I_F = 350mA):

Code	Min.	Max.	Unit
UV325	320	330	200
UV335	330	340	nm

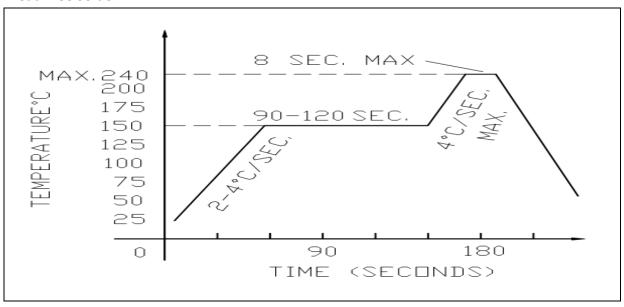






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Recommended reflow temperature 240°C. Maximum soldering temperature should be limited to 245°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.

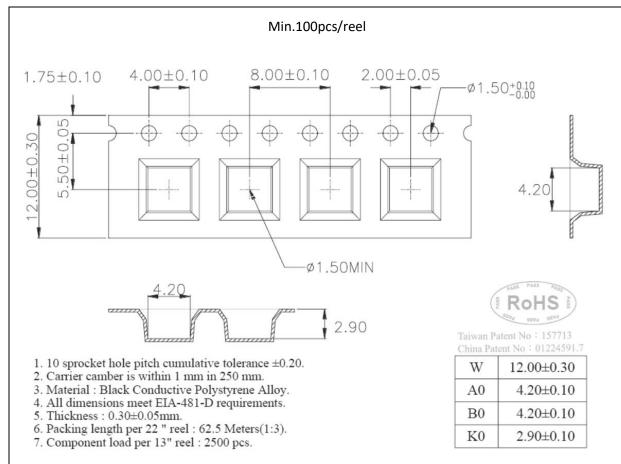


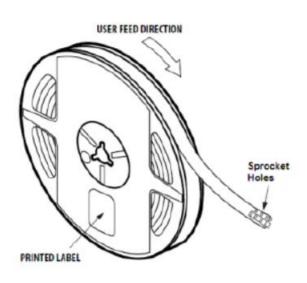




PACKING SPECIFICATION:

Reel Dimension:











PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 72 hours. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

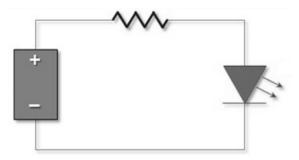
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±3°C x 12hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.







REVISION RECORD:

Version	Date	Summary of Revision
A1.0	22/06/2022	Datasheet set-up.
A1.1	22/01/2023	Update wavelength binning.